



Material Content Data Sheet



Sales Product Name				SAK-TC234LP-32F200N AC		Issued		4. July 2019	
MA#				MA001654634					
Package				PG-TQFP-144-27		Weight*		699.45 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	23.351	3.34	3.34	33385	33385	
leadframe	inorganic material	phosphorus	7723-14-0	0.066	0.01		95		
	non noble metal	zinc	7440-66-6	0.265	0.04		379		
	non noble metal	iron	7439-89-6	5.302	0.76		7580		
wires	non noble metal	copper	7440-50-8	215.278	30.78	31.59	307782	315836	
	noble metal	gold	7440-57-5	0.002	0.00		3		
	noble metal	palladium	7440-05-3	0.042	0.01		59		
encapsulation	non noble metal	copper	7440-50-8	1.844	0.26	0.27	2636	2698	
	organic material	carbon black	1333-86-4	1.328	0.19		1899		
	plastics	epoxy resin	-	56.224	8.04		80383		
leadfinish	inorganic material	silicondioxide	60676-86-0	385.155	55.07	63.30	550651	632933	
	noble metal	palladium	7440-05-3	0.003	0.00		4		
	noble metal	silver	7440-22-4	0.003	0.00		4		
plating	noble metal	gold	7440-57-5	0.005	0.00		7		
	non noble metal	nickel	7440-02-0	4.713	0.67	0.67	6739	6754	
	noble metal	palladium	7440-05-3	0.000	0.00		1		
glue	noble metal	silver	7440-22-4	0.000	0.00		1		
	noble metal	gold	7440-57-5	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.366	0.05	0.05	523	526	
*deviation	plastics	epoxy resin	-	1.211	0.17		1731		
	noble metal	silver	7440-22-4	4.292	0.61	0.78	6137	7868	
						Sum in total:	100.00	1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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